

Serial No. 09/868,566

Art Unit: 1712

DISCUSSION

The claims have been amended to more particularly point out and clearly define what Applicants consider to be their invention. The limitations of claim 26 have been modified and entered into claim 15. Claim 26 has been canceled. Claim 28 has been amended to claim a method for bonding utilizing a particular composition in which the cured adhesive forms a bond with particular properties. Applicants respectfully submit that the amendments to claim 28 are fully supported in the specification and claims as originally filed. New claims 31, 32 and 33 have been entered in the application. The limitations of claims 31, 32 and 33 are fully supported in the specification and claims as originally filed.

Applicants respectfully submit that the amendments to the claims are fully supported in the specification and claims as originally filed and no new matter has been entered by way of amendment to the claims.

In the official action, the Examiner indicated that claims 26-30 were objected to but would be allowable if amended. Claim 15 has been amended to include the limitations of claim 26. Applicants therefore respectfully submit that claims 15-25 are in condition for allowance.

Claim 27 has been made dependent upon claim 23 which should be allowable. Applicants therefore respectfully submit that claim 27 is allowable.

Claim 28 has been amended to claim a process which utilizes a particular composition for bonding substrates. As claimed in claim 28, the method provides an adhesive joint which has particular low temperature and high temperature properties. Applicants therefore respectfully submit that claim 28 and claims dependent thereon are in condition for allowance.

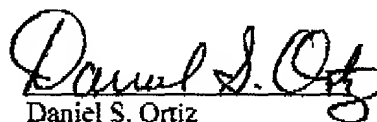
The prior art cited by the Examiner neither teaches nor suggests the favorable low temperature properties possessed by the adhesive bond of the present invention after it has been cured. Applicants therefore respectfully submit that Mülhaupt et al.(US 5,278,257) neither teaches nor suggests the present invention.

To be a proper reference on which a rejection under 35 USC 102(b) can be based, the reference must disclose each and every limitation in the claims. Clearly, Mülhaupt et al. is completely silent concerning any low temperature properties of a cured adhesive. Applicants therefore respectfully request favorable consideration of the claims in their amended form.

Serial No. 09/868,566
Art Unit. 1712

In view of the amendments entered in the claims and the above discussion, Applicants respectfully submit that the application is in condition for allowance and favorable consideration is requested.

Respectfully submitted,



Daniel S. Ortiz
(Reg. No. 25,123)
Attorney/Agent for Applicant
(610) 278-4934

Henkel Corporation
Law Department
1500 Renaissance Blvd.- Suite 200
Gulph Mills, PA 19406

OFFICIAL

RECEIVED
CENTRAL FAX CENTER
SEP 10 2003